



Thyristor Module

Features

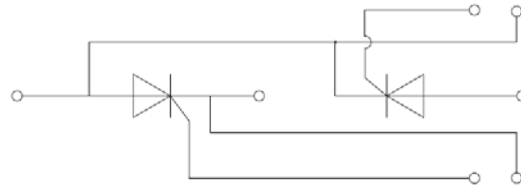
- Half-bridge SCR configuration integrated in a single package
- High-thermal-conductivity DBC insulation for excellent heat dissipation
- Vacuum soldering technology for enhanced reliability

Product Summary

Parameter	Value	Unit
V_{RRM}	1600	V
$I_{T(AV)}$ (@ $T_C = 85^\circ$)	160	A
I_{TSM} (@ $t_P = 10ms$)	3200	A
V_T (Max)	1.80	V

Applications

- Heating control
- Light control system
- DC motor



Absolute Maximum Ratings (@ $T_C = 25^\circ C$ unless otherwise specified)

Parameter	Conditions	Symbol		
Non-repetitive peak offstate voltage	$T_{vj} = 25^\circ C$	V_{DSM}	1700	V
Non-repetitive peak reverse voltage	$T_{vj} = 25^\circ C$	V_{RSM}	1700	V
Average forward current	$T_C = 85^\circ C$	$I_{T(AV)}$	160	A
Forward surge current	1/2 cycle, Sine wave, 50Hz $T_{vj} = 25$	I_{TSM}	3200	A
I^2t value for fusing		I^2t	51200	A^2s
Critical rate of rise of on-state current	$I_G = 2 \times I_{GT}$	di/dt	150	$A/\mu s$
RMS isolation voltage	A.C 50Hz(1s/1min)	V_{ISO}	3600/3000	V
Junction temperature range		T_J	-40 ~ +125	
Storage temperature range		T_{stg}	-40 ~ +125	





Ordering Information

Device	Marking	Package	Weight	Inner Box	Pre Carton
JMT160KT16T2C	JMT160KT16T2C	T2	170 10g	6 PCS	72 PCS

Typical Electrical & Thermal Characteristics

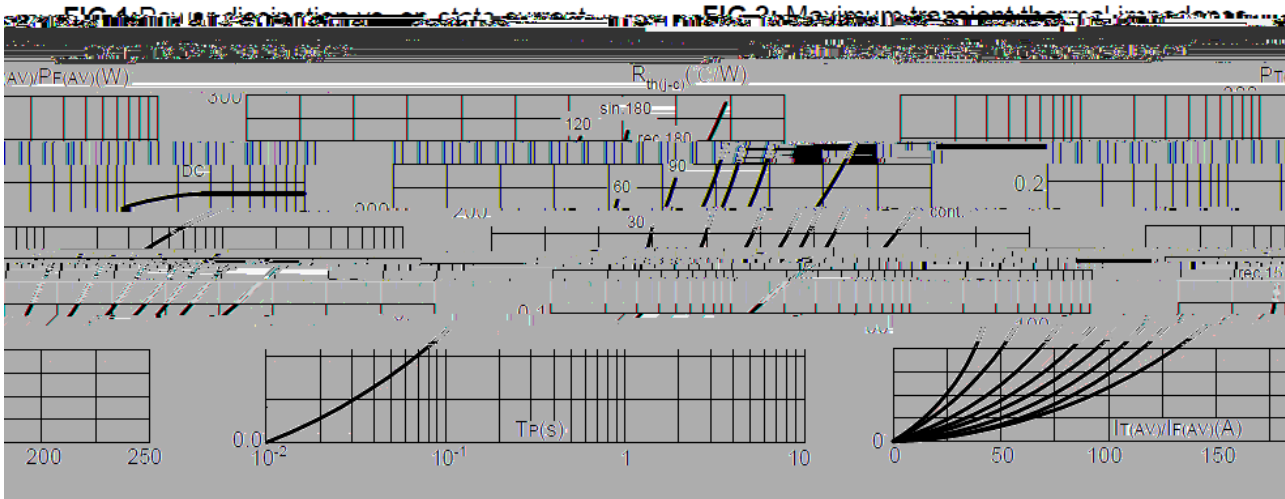
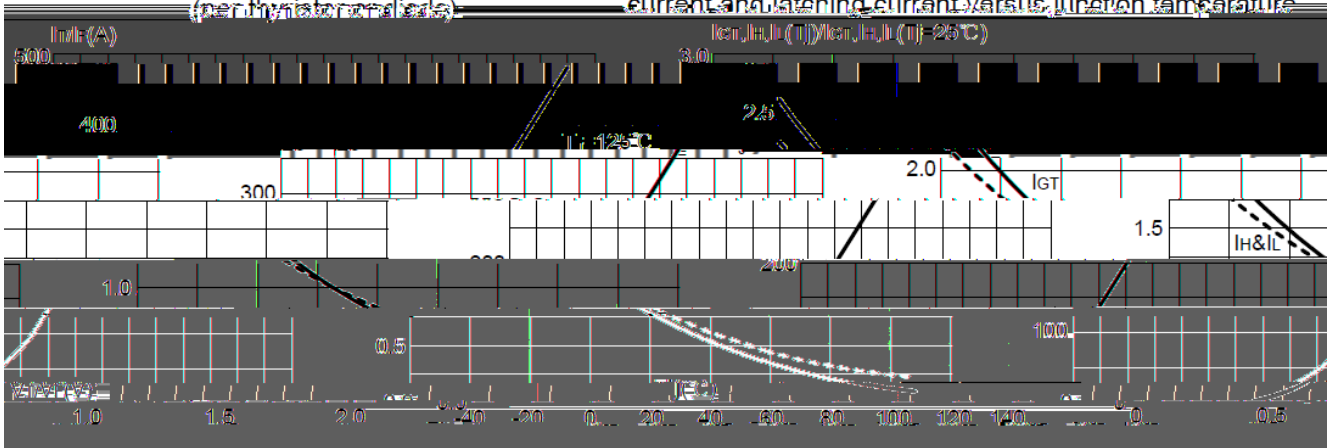


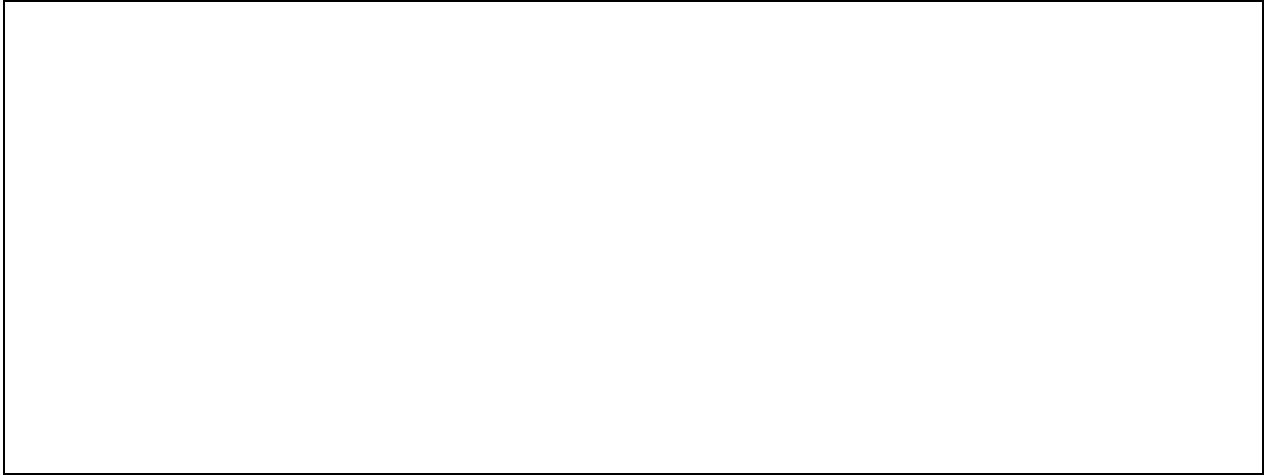
FIG.3: Forward characteristics (per thyristor anode)

FIG.4: Relative variations of gate trigger current, holding current and latching current versus junction temperature





Circuit Diagram



Package Outlines (mm)



Unit of measurement: mm



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